



Material Content Data Sheet



Sales Product Name		BCR 505 E6327		Issued		29. August 2013		
MA#		MA000238828						
Package		PG-SOT23-3-5		Weight*		9.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		14	
	noble metal	gold	7440-57-5	0.013	0.14		1393	
	inorganic material	silicon	7440-21-3	0.112	1.19	1.33	11900	13307
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		964	
	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		321	
	non noble metal	copper	7440-50-8	3.000	32.01	32.15	320052	321401
wire	noble metal	gold	7440-57-5	0.021	0.22	0.22	2219	2219
encapsulation	organic material	carbon black	1333-86-4	0.046	0.49		4934	
	plastics	brominated resin	-	0.058	0.62		6168	
	inorganic material	antimonytrioxide	1309-64-4	0.116	1.23		12335	
	plastics	epoxy resin	-	1.052	11.23		112253	
	inorganic material	silicondioxide	60676-86-0	4.510	48.10	61.67	481082	616772
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	15962	15962
plating	noble metal	silver	7440-22-4	0.284	3.03	3.03	30339	30339
*deviation	< 10%				Sum in total:		100,00	1000000

Important Remarks:

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